## **TRANSMITTAL**

Electronic Version v1.1

Stylesheet Version v1.1.0

## Title of Invention

ANOLYTE FOR COPPER PLATING

Application Number:

10/616044

6044

Date:

2003-07-08

First Named Applicant:

Mr. Yang Michael X.

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9799

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APPM/7669P2

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Documents being submitted:	Files	
us-ids	APPM7669P2BTP-usidst.xml	
	us-ids.dtd	
	us-ids.xsl	
us-fee-sheet	APPM7669P2BTP-usfees.xml	
	us-fee-sheet.xsl	
	us-fee-sheet.dtd	
Comments		